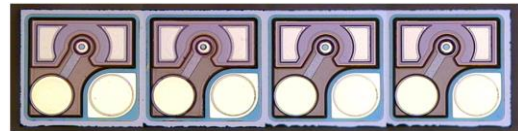


Features

- : Multi-mode 850nm wavelength range
- : Data Rate up to 25Gbps
- : 1x4 chips
- : Two top-side wire bond pads

Description



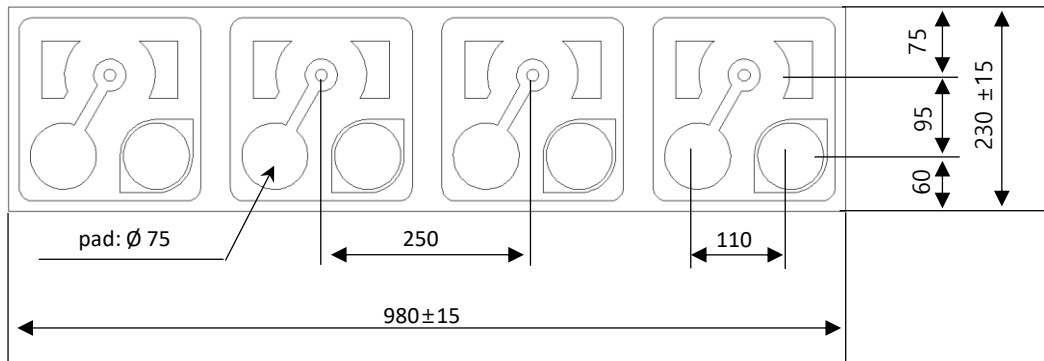
Applications

- : High speed Data Communications
- : Gigabit Ethernet
- : Fiber Channel

Absolute Maximum Ratings

Parameter	Rating
Storage Temperature	-40 to 100 °C
Operating Temperature	-40 to 85 °C
Continuous Forward Current	10mA
Continuous Reverse Voltage	5V (@10μA)

Dimensions



unit : μm

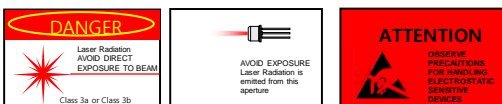
Die Height : 150 ± 15 μm

Electro-Optics Characteristics ($T_a=25^\circ\text{C}$ unless otherwise stated)

Parameters	Symbol	Specified			Unit	Test Conditions
		Min.	Typ.	Max.		
Threshold Current	I_{th}		0.6		mA	CW
I_{th} Temperature Variation	ΔI_{th}		1.0		mA	$T_a = -40$ to 85°C
I_{th} Uniformity within Array	ΔI_{th}^a			0.2	mA	CW
Slope Efficiency	η		0.5		W/A	$I_f = 6\text{mA}$
η Temperature Variation	$\Delta\eta / \Delta T$		-0.4		%/ $^\circ\text{C}$	$T_a = -40$ to 85°C at 6mA
Optical Output Power	P_o		3.5		mW	$I_f = 6\text{mA}$
P_o Uniformity within Array	ΔP_o^a			0.3	mW	$I_f = 6\text{mA}$
Peak Wavelength	λ	840	850	860	nm	$I_f = 6\text{mA}$, R.T
λ Temperature Variation	$\Delta\lambda / \Delta T$		0.06		nm/ $^\circ\text{C}$	$T_a = -40$ to 85°C at 6mA
Spectral Bandwidth (RMS)	$\Delta\lambda$			0.65	nm	$I_f = 6\text{mA}$
Beam Divergence	Θ	14		33	$^\circ$	$I_f = 6\text{mA}$ (Full Width, $1/e^2$)
Operating Voltage	V_f		2.2	2.6	V	$I_f = 6\text{mA}$
Breakdown Voltage	V_b		-8		V	
Dynamic Resistance	R_d		80	100	Ohm	$I_f = 6\text{mA}$
Small Signal Bandwidth	f_{-3dB}		18		GHz	$I_f = 6\text{mA}$, R.T

Notes

* These specifications are subject to change without notice.



NOTICE	The inherent design of this component causes it to be sensitive to electrostatic discharge(ESD). To prevent ESD-induced damage and/or degradation to equipment, take normal ESD precautions when handling this product
DANGER	The VCSEL is a class IIIb laser and should be treated as a potential eye hazard. Due to the size of the component, the applicable warning logotype, aperture label, and certification / identification label cannot be placed on the component itself.